In the claims

1(Currently Amended). A capacitor, comprising:

a first nickel electrode electrically connected to an aluminum lead of an integrated circuit and applied on a passivation layer of the integrated circuit;

a BCTZ dielectric covering a side of the first nickel; and

a second nickel electrode sandwiching the BCTZ~~, wherein the first nickel electrod, the BCTZ dielectric and the second nickel electrode are contained within a bump of an integrated circuit~~.

2(Original). The capacitor of claim 1, wherein the BCTZ contains from eighty eight to one hundred atoms of barium for every twelve to zero atoms of calcium.

3(Original). The capacitor of claim 1, wherein the BCTZ contains eighty two to ninety atoms of titanium for each ten to eighteen atoms of zirconium.

4(Currently Amended). The capacitor of claim 1, wherein the first nickel electrode is adjacent to an aluminum lead on ~~an~~ the integrated circuit.

5(Previously Presented). The capacitor of claim 4, wherein the second nickel electrode is electrically connected to a second aluminum lead on the integrated circuit.

6(Previously Presented) The capacitor of claim 5, wherein the second nickel electrode is a base for solder to be reflowed to form the bump.